Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.038”**

**ANODE**

**.0215 x .0215”**

**.038”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .0215”**

**Backside Potential: Cathode**

**APPROVED BY: DK DIE SIZE .038” X .038” DATE: 10/21/21**

**MFG: AEROFLEX/KNOX/MM THICKNESS .011 P/N: 1N4101**

**DG 10.1.2**

#### Rev B, 7/19/02